# LNJ03004BLD3

### Surface Mounting Chip LED

3230 Type

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	430	mW	
Forward current *1	I <sub>F</sub>	120	mA	
Pulse forward current *2	I <sub>FP</sub>	200	mA	
Junction temperature	Tj	110	°C	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Lighting Color

• White (2700 [Kelvin])

Note) \*1:  $I_F$  is different by radiated factor of evaluation board.

This value is mounted on evaluation board at Rthj-a = 35.0 °C/W.

\*2: The condition of pulse current  $I_{FP}$  is 55 ms pulse width, 10 % duty.

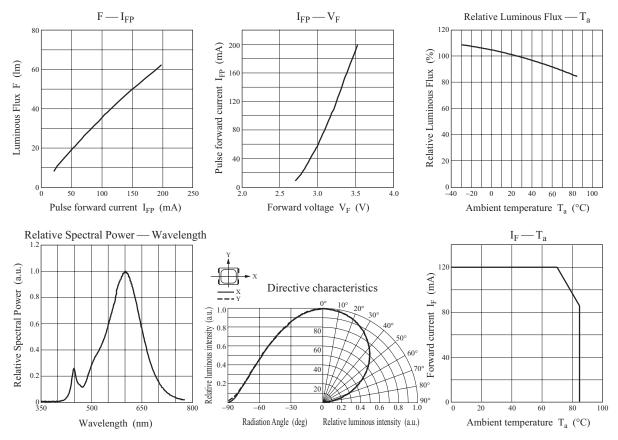
#### Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage *1	V <sub>F</sub>	$I_{\rm FP} = 60  {\rm mA}$	2.6	3.0	3.4	V
Luminous flux *2	F	$I_{\rm FP} = 60  {\rm mA}$	18.0	22.6	36.0	lm
Chromaticity coordinates *3	х	$I_{\rm FP} = 60  {\rm mA}$		0.459		
	у	$I_{\rm FP} = 60  {\rm mA}$		0.412		
Color Rendering Index	Ra	$I_{\rm FP} = 60  {\rm mA}$		82		

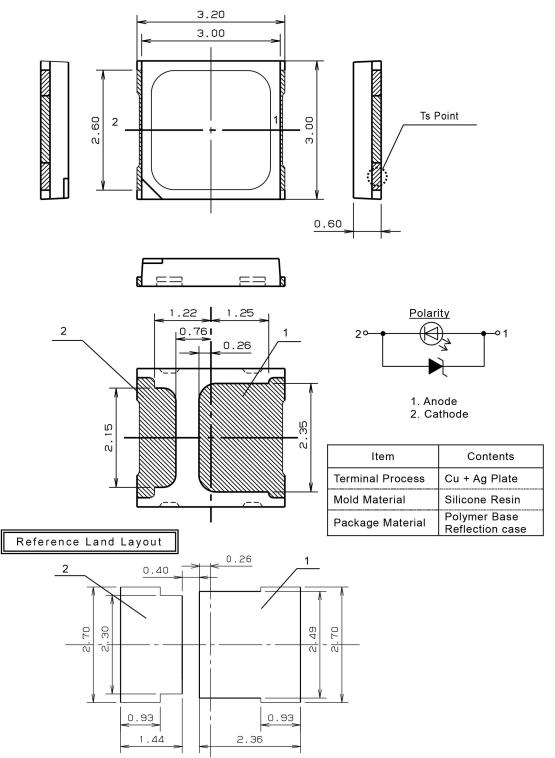
Note) \*1: Complete Forward Voltage measurement within 0.1 seconds. Tolerance ±3%

\*2: Complete Luminous flux measurement within 0.1 seconds. Tolerance  $\pm 10\%$ 

\*3: Complete Chromaticity coordinates measurement within 0.1 seconds. Tolerance of chromaticity is ±0.01



Package (Unit: mm)



(Note1) Tolerance unless otherwise specified :  $\pm 0.2mm$ 

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